

Global Advanced Bonding Equipment Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

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Abstracts

According to our (Global Info Research) latest study, the global Advanced Bonding Equipment market size was valued at US\$ 992 million in 2025 and is forecast to a readjusted size of US\$ 1680 million by 2032 with a CAGR of 7.3% during review period.

Advanced Bonding Equipment should be defined as the set of core process tools used to create high-precision, high-cleanliness, and high-reliability bonded interfaces across wafer-to-wafer (W2W), die-to-wafer (D2W/C2W), and chip-to-chip (C2C) structures, mainly for heterogeneous integration, 3D stacking, ultra-fine-pitch interconnects, ultra-thin wafer support, hermetic/vacuum packaging, and low-temperature or room-temperature material integration. The scope should include two major categories: wafer bonding equipment, covering permanent bonding, direct/fusion bonding, hybrid bonding, room-temperature/surface-activated bonding, anodic bonding, wafer-level thermo-compression/metal diffusion bonding, and temporary bonding/debonding; and advanced chip bonding equipment, but only when the tools are explicitly designed for hybrid bonding, direct bonding, or thermo-compression bonding (TCB) in high-density interconnect applications. By contrast, conventional die bonders, wire bonders, and standard flip-chip bonders should be excluded because they are primarily general assembly, wire interconnect, or standard packaging placement tools rather than advanced bond-interface formation platforms.

In practical industry terms, advanced bonding equipment has evolved from a market once centered on MEMS, CIS, engineered substrates, and wafer-level packaging into a strategic equipment segment increasingly driven by advanced packaging, HBM, chiplets, 2.5D/3D integration, AI, and HPC. The clearest technology trajectory today is that W2W hybrid bonding has already developed a relatively solid foundation in

applications such as CIS and NAND, while D2W/C2W hybrid bonding is accelerating with chiplet and HBM demand; temporary bonding/debonding has become a key enabler for wafer thinning and stacked-device manufacturing; and equipment platforms are moving toward more integrated, modular, and production-oriented architectures combining cleaning, activation, metrology, bonding, and debonding. SUSS explicitly positions TBDB as a core platform and hybrid bonding as a growth vector, while Applied Materials' Kinex integrates wet clean, plasma activation, degas, metrology, and bonding into a unified high-volume platform. Besi, ASMPT, Shibaura, and SET are also reinforcing their hybrid bonding and TCB portfolios.

The major growth drivers for advanced bonding equipment can be summarized into four dimensions. First, AI, HPC, HBM, and chiplet architectures are increasing demands for bandwidth density, interconnect density, and energy efficiency, accelerating the adoption of hybrid bonding and TCB. Second, ultra-thin wafer thinning, transport, and stacking are driving stronger demand for temporary bonding and debonding. Third, applications such as MEMS, CIS, engineered substrates, power devices, compound semiconductors, and III-V/optical devices continue to require lower thermal budgets, higher vacuum capability, lower particle levels, and broader material compatibility. Fourth, as advanced packaging faces simultaneous pressure on yield and cost, equipment competition is shifting toward overlay accuracy, cleanliness control, inline metrology, void/defect suppression, and overall cost-of-ownership optimization. As a result, advanced bonding equipment should be viewed not simply as a packaging sub-segment, but as a cross-domain strategic equipment category linking front-end material engineering, wafer processing, and advanced integration.

This report is a detailed and comprehensive analysis for global Advanced Bonding Equipment market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Advanced Bonding Equipment market size and forecasts, in consumption value (\$ Million), sales quantity (Units), and average selling prices (US\$/Unit), 2021-2032

Global Advanced Bonding Equipment market size and forecasts by region and country,

in consumption value (\$ Million), sales quantity (Units), and average selling prices (US\$/Unit), 2021-2032

Global Advanced Bonding Equipment market size and forecasts, by Type and by Application, in consumption value (\$ Million), sales quantity (Units), and average selling prices (US\$/Unit), 2021-2032

Global Advanced Bonding Equipment market shares of main players, shipments in revenue (\$ Million), sales quantity (Units), and ASP (US\$/Unit), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for Advanced Bonding Equipment

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global Advanced Bonding Equipment market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include EV Group, SUSS MicroTec, Tokyo Electron, Applied Microengineering Ltd (AML), Nidec Machine Tool, Ayumi Industry, Shanghai Micro Electronics, U-Precision Tech, Hutem, Canon, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Advanced Bonding Equipment market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Wafer Bonding Equipment

Chip Bonding Equipment

Market segment by Degree of Automation

Fully Automatic Bonding Equipment

Semi Automatic Bonding Equipment

Market segment by Bonding Technology

Permanent Bonding

Temporary Bonding/Debonding

Market segment by Application

Advanced Packaging & Heterogeneous Integration

MEMS/Sensor Packaging

CIS

RF / Photonics / Compound-Semiconductor Devices

Major players covered

EV Group

SUSS MicroTec

Tokyo Electron

Applied Microengineering Ltd (AML)

Nidec Machine Tool

Ayumi Industry

Shanghai Micro Electronics

U-Precision Tech

Hutem

Canon

Bondtech

TAZMO

Aimechatec

Besi

ASMPT Ltd

Applied Materials

Shibaura Mechatronics

SET (Smart Equipment Technology)

Kostek Systems

Mycronic

Kulicke & Soffa

Saultech Technology

Skytech Group

BestBon Co., Ltd.

iSABers Group

Suzhou iWISEETEC

Piotech, Inc

Kingsemi

Wisdom Semiconductor Technology

Suzhou Maxwell Technologies

Qinghui Semiconductor

Sintaike Semiconductor Equipment (Shanghai) Co., Ltd.

Larcom Semiconductor Equipment (Shanghai) Co., Ltd.

Wushi Microelectronics (Suzhou) Co., Ltd.

Bio-Nano Semi-conductor Equipment (ZheJiang) Co.,Ltd

Haichuang Intelligent Equipment (Yantai) Co., Ltd.

Circuit Fabology Microelectronics Equipment

iSTAR

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Advanced Bonding Equipment product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Advanced Bonding Equipment, with price, sales quantity, revenue, and global market share of Advanced Bonding Equipment from 2021 to 2026.

Chapter 3, the Advanced Bonding Equipment competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Advanced Bonding Equipment breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026. and Advanced Bonding Equipment market forecast, by regions, by Type, and by Application, with sales and revenue, from 2027 to 2032.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Advanced Bonding Equipment.

Chapter 14 and 15, to describe Advanced Bonding Equipment sales channel, distributors, customers, research findings and conclusion.

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